



S/N 10/607,782

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Sabina J. Houle
Serial No.: 10/607,782
Filed: June 27, 2003
Title: LIQUID SOLDER THERMAL INTERFACE MATERIAL CONTAINED
WITHIN A COLD-FORMED BARRIER AND METHODS OF MAKING
SAME
Assignee: Intel Corporation
Customer No: 21186

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action mailed on November 24, 2004. Please amend the above-identified patent application as follows.

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